PTO/SB/21 (08-00)
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TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

Application Number	09/881,514				
Filing Date	06/12/2001				
First Named Inventor	Solomon I. Beilin				
Group Art Unit	1765				
Examiner Name	Shamim Ahmed				
Attorney Docket Number	6136/60403 (25916-226)	_			

Total Number of Pages in This Submission 14 Attorney Docket Number 6136/60403 (25916-2	.20)					
ENCLOSURES (check all that apply)						
Fee Transmittal Form Assignment Papers (for an Application)	Board es Group					
under 37 CFR 1.52 or 1.53						
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT						
Firm or Individual name Coudert Brothers LLP	Coudert Brothers LLP					
Signature Stan RVoz						
Date 12/24/2002						
CERTIFICATE OF MAILING						
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Typed or printed name Mary M. Padilla						
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PTO/SB/17 (10-02)

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FEE TO AND	CRAITTA	Co	Complete if Known					
FEE TRANS	DIVITI I A	Application Number	09/881,514					
for FY	2003	Filing Date	06/12/2001 Solomon I. Beilin Shamim Ahmed					
Patent fees are subject to		First Named Inventor						
		Examiner Name						
Applicant claims small entity status. See 37 CFR 1.27		Art Unit	1765					
TOTAL AMOUNT OF PAYMENT	(\$) 168.00	Attorney Docket No.	6136/60403 (25916-226)					
METHOD OF DAYMENT (sheets ell that annie)		EEE CA	EEE CALCUL ATION (continued)					

METHOD OF PAYMENT (check all that apply)				FEI	E CALCULATION (continued)	
X Check Credit card Money Other None	3. ADDITIONAL FEES Large Entity Small Entity				<u>ر</u> ک	
Deposit Account:		Entity	Smal	I Entity	· · · · · · · · · · · · · · · · · · ·	
Deposit	Fee Code	Fee (\$)	Fee Code	Fee (\$)	Fee Description CFee	Daid
Account Number 13–0201	1051	130	2051	65	Surcharge - late filing fee or oath	
Deposit Account Coudert Brothers LLP	1052	50	2052	25	Surcharge - late provisional filing fee or cover sheet	二
Name The Commissioner is authorized to: (check all that apply)	1053	130	1053	130	Non-English specification	
Charge fee(s) indicated below	l	2,520	1812		For filing a request for ex parte reexamination	-
Charge any additional fee(s) during the pendency of this application	1804	920*	1804	920*	Requesting publication of SIR prior to Examiner action	
Charge fee(s) indicated below, except for the filing fee to the above-identified deposit account.	1805	1,840*	1805	1,840*	Requesting publication of SIR after Examiner action	
FEE CALCULATION	1251	110	2251	55	Extension for reply within first month	ŀ
1. BASIC FILING FEE	1252	400	2252	200	Extension for reply within second month	
Large Entity Small Entity	1253	920	2253	460	Extension for reply within third month	— ∤
Fee Fee Fee Fee Fee Paid Code (\$) Code (\$)	1254	1,440	2254	720	Extension for reply within fourth month	
1001 740 2001 370 Utility filing fee	1255	1,960	2255	980	Extension for reply within fifth month	 -⊦
1002 330 2002 165 Design filing fee	1401	320	2401	160	Notice of Appeal	
1003 510 2003 255 Plant filing fee	1402	320	2402	160	Filing a brief in support of an appeal	
1004 740 2004 370 Reissue filing fee	1403	280	2403	140	Request for oral hearing	-
1005 160 2005 80 Provisional filing fee	1451	1,510	1451	1,510	Petition to institute a public use proceeding	
SUBTOTAL (1) (\$) -0-	1452	110	2452	55	Petition to revive - unavoidable	—-
		1,280	2453	640	Petition to revive - unintentional	 i
2. EXTRA CLAIM FEES FOR UTILITY AND REISSUE		1,280	2501	640	Utility issue fee (or reissue)	
Extra Claims below Fee Paid Total Claims X	1502	460	2502		Design issue fee	
Independent 2 × 84 168	1503	620	2503	310	Plant issue fee	
Claims -3 - 2 ^ 4 4 100 Multiple Dependent	1460	130	1460	130	Petitions to the Commissioner	
	1807	50	1807	50	Processing fee under 37 CFR 1.17(q)	
Large Entity Small Entity Fee Fee Fee Fee <u>Fee Description</u>	1806	180	1806	180	Submission of Information Disclosure Stmt	
Code (\$) Code (\$)	8021	40	8021	40	Recording each patent assignment per property (times number of properties)	
1202 18 2202 9 Claims in excess of 20 1201 84 2201 42 Independent claims in excess of 3	1809	740	2809	370	Filing a submission after final rejection (37 CFR 1.129(a))	
1203 280 2203 140 Multiple dependent claim, if not paid	1810	740	2810	370		
1204 84 2204 42 ** Reissue independent claims over original patent	1801	740	2801	370	examined (37 CFR 1.129(b)) Request for Continued Examination (RCE)	
1205 18 2205 9 ** Reissue claims in excess of 20 and over original patent	1802	900	1802	900	Request for expedited examination of a design application	
			ecify) _			
SUBTOTAL (2) [(\$) 168.00 **or number previously paid, if greater; For Reissues, see above	*Redu	iced by	Basic	Filing F	Fee Paid SUBTOTAL (3) (\$) -0-	

SUBMITTED BY			(Complete	e (if applicable)
Name (Print/Type)	Steven R. Vosen, Ph.D.	Registration No. (Attorney/Agent) 45,18	36 Telephone	° 415/409–2900
Signature	Stade		Date	12/24/2002

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s):

Solomon I. Beilin, et al.

Serial No.:

09/881,514

Filed:

June 12, 2001

For:

METHODS OF PLANARIZING

STRUCTURES ON WAFERS AND SUBSTRATES BY

POLISHING

Group Art Unit:

1765

Examiner:

Shamim Ahmed

Attorney Docket:

6136/60403(25916-226)

CERTIFICATE OF MAILING/TRANSMISSION (37 C.F.R. § 1.8A)

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Washington, D.C. 20231.

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December 24, 2002

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ary M. Padilla

AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

The following Amendment and Remarks are made in response to the Office Action mailed September 24, 2002. Reexamination and reconsideration of the application in light of the following Amendment and Remarks are respectfully requested.

In the Specification:

Please replace the paragraph beginning on Page 14, line 9 through the beginning of Table II with the following paragraph:

The removal rate of tungsten was found to be lower in acidic slurries than in alkaline slurries, and this is believed to be due to the formation of an oxide layer over the tungsten in acidic (low pH) slurries. This oxide layer retards the chemical-mechanical polishing of tungsten. Therefore, it is desirable to polish the samples in acidic slurries so that a thin tungsten layer can hold up longer and serve more effectively as a polish-stop layer. The chemistry of commercial slurries was modified by adding various acids to adjust the pH to be within the acidic range (pH < 7.0), and the effects of these acids on polish selectivity were experimentally studied by examining the chemical etching rate of copper, polyimide, and

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